

REMARKS

This is a full and timely response to the non-final Office Action mailed February 27, 2003 (Paper No. 4). Reexamination and reconsideration in light of the above amendments and following remarks are courteously requested.

Claims 1-20 are now pending in the application, with Claims 1, 11, and 18 being the independent claims. Claims 1-7, 9-12, 14, and 16-19 have been amended, and Claim 20 is newly presented herein. No new matter is believed to have been added.

Rejections under 35 U.S.C. § 103

Claims 1-3, 5-9, 11-16, 18, and 19 were rejected under 35 U.S.C. § 103 as allegedly being unpatentable over U.S. Patent Nos. 5,295,045 (Kitano et al.) and 6,224,405 (Eland). This rejection is respectfully traversed.

Independent Claim 1 relates to a circuit package for an electronic device that includes first and second circuit boards positioned in first and second planes, respectively, and recites, *inter alia*, a housing formed between the first and second circuit boards and configured to substantially cover at least one surface of each circuit board and leave another surface of each circuit board substantially uncovered to thereby expose the uncovered surface to an environment exterior of the circuit package. Independent Claim 18 relates to a method of making the circuit package recited in independent Claim 1.

Independent Claim 11 relates to a circuit package for an electronic device that includes first and second circuit boards positioned in first and second planes, respectively, and a housing that is formed to surround at least a portion of the first and second circuit boards, and recites, *inter alia*, that the second circuit board is in contact with the first circuit board.

Kitano et al. relates to a plastic-molded-type semiconductor device that includes a plurality of semiconductor chips (1a, 1b, 1c) that are spaced apart from one another and arranged in different planes. The semiconductor chips are disposed within a resin housing (6) that fully encapsulates the chips (FIGS. 1-11, 13; col. 4, ll. 35-56). Thus, Kitano et al. fails to disclose at least the above-noted features of independent Claims 1 and 11. Namely, Kitano et al. fails to disclose at least a housing formed between the first and second circuit boards and configured to substantially cover at least one surface of the each circuit board and leave another surface of each circuit board substantially uncovered to thereby expose the uncovered surface to an environment exterior of the circuit package, as recited in independent Claim 1. Kitano et al. additionally fails

to disclose that the second circuit board is in contact with the first circuit board, as recited in independent Claim 11. Moreover, Applicants submit that Kitano et al. fails to disclose a method of making the circuit package, as recited in independent Claim 18.

Eland relates to an electrical connector having an ejector mechanism. The connector includes ejector pads (46) for engaging a circuit board surface (48) (col. 3, ll. 4-5). However, Eland is not understood to make up at least for the deficiencies of Kitano et al., noted above with respect to independent Claims 1, 11, and 18.

Therefore, reconsideration and withdrawal of the § 103 rejection is respectfully solicited.

Based on the above, independent Claims 1, 11, and 18 are patentable over the citations of record. The dependent claims 2-10, 12-17, 19, and 20 are also submitted to be patentable for the reasons given above with respect to the independent Claims and because each recites features which are patentable in its own right. Individual consideration of the dependent claims is respectfully solicited.

The other art of record is also not understood to disclose or suggest the inventive concept of the present invention as defined by the claims.

Conclusion

Applicant submits that the present application is in condition for allowance. Favorable reconsideration and withdrawal of the objections and rejections set forth in the above-noted Office Action, and an early Notice of Allowance are requested.

If the Examiner has any comments or suggestions that could place this application in even better form, the Examiner is requested to telephone the undersigned attorney at the below-listed number.

Respectfully submitted,

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By: 

Paul D. Amrozowicz
Reg. No. 45,264
(480) 385-5060

Ingrassia Fisher & Lorenz
Customer No. 29906